



ABSTRACT

In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of semiconductor structure, the improvement comprising: an integrated metal etch tool comprising separate chamber means for

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forming a water-only plasma process to strip the photo-resist layer of a semiconductor composite structure previously subjected to a RIE process; and separate chamber means for

supplying a mixture of an etching gas and an acid neutralizing gas into a vacuum chamber in which the structure is supported to form a water soluble material of sidewall polymer rails left behind on the Al/Cu metal line from the RIE process, thereby permitting removal of the water soluble material with deionized water.

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